Freescale Semiconductor - MCF52221CAF80 Datasheet

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	Coldfire V2
Core Size	32-Bit Single-Core
Speed	80MHz
Connectivity	I²C, SPI, UART/USART, USB OTG
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	56
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 8x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	100-LQFP (14x14)
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=mcf52221caf80

  - Interchip bus interface for EEPROMs, LCD controllers, A/D converters, and keypads
  - Fully compatible with industry-standard I^2C bus
  - Master and slave modes support multiple masters
  - Automatic interrupt generation with programmable level
- Queued serial peripheral interface (QSPI)
  - Full-duplex, three-wire synchronous transfers
  - Up to four chip selects available
  - Master mode operation only
  - Programmable bit rates up to half the CPU clock frequency
  - Up to 16 pre-programmed transfers
- Fast analog-to-digital converter (ADC)
  - Eight analog input channels
  - 12-bit resolution
  - Minimum 1.125 µs conversion time
  - Simultaneous sampling of two channels for motor control applications
  - Single-scan or continuous operation
  - Optional interrupts on conversion complete, zero crossing (sign change), or under/over low/high limit
  - Unused analog channels can be used as digital I/O
- Four 32-bit timers with DMA support
  - 12.5 ns resolution at 80 MHz
  - Programmable sources for clock input, including an external clock option
  - Programmable prescaler
  - Input capture capability with programmable trigger edge on input pin
  - Output compare with programmable mode for the output pin
  - Free run and restart modes
  - Maskable interrupts on input capture or output compare
  - DMA trigger capability on input capture or output compare
- Four-channel general purpose timer
  - 16-bit architecture
  - Programmable prescaler
  - Output pulse-widths variable from microseconds to seconds
  - Single 16-bit input pulse accumulator
  - Toggle-on-overflow feature for pulse-width modulator (PWM) generation
  - One dual-mode pulse accumulation channel
- Pulse-width modulation timer
  - Operates as eight channels with 8-bit resolution or four channels with 16-bit resolution
  - Programmable period and duty cycle
  - Programmable enable/disable for each channel
  - Software selectable polarity for each channel
  - Period and duty cycle are double buffered. Change takes effect when the end of the current period is reached (PWM counter reaches zero) or when the channel is disabled.
  - Programmable center or left aligned outputs on individual channels
  - Four clock sources (A, B, SA, and SB) provide for a wide range of frequencies
  - Emergency shutdown
- Two periodic interrupt timers (PITs)

1.2.7 USB On-The-Go Controller

The device includes a Universal Serial Bus On-The-Go (USB OTG) dual-mode controller. USB is a popular standard for connecting peripherals and portable consumer electronic devices such as digital cameras and handheld computers to host PCs. The OTG supplement to the USB specification extends USB to peer-to-peer application, enabling devices to connect directly to each other without the need for a PC. The dual-mode controller on the device can act as a USB OTG host and as a USB device. It also supports full-speed and low-speed modes.

1.2.8 UARTs

The device has three full-duplex UARTs that function independently. The three UARTs can be clocked by the system bus clock, eliminating the need for an external clock source. On smaller packages, the third UART is multiplexed with other digital I/O functions.

1.2.9 I^{2}C Bus

The I^{2}C bus is an industry-standard, two-wire, bidirectional serial bus that provides a simple, efficient method of data exchange and minimizes the interconnection between devices. This bus is suitable for applications requiring occasional communications over a short distance between many devices.

1.2.10 QSPI

The queued serial peripheral interface (QSPI) provides a synchronous serial peripheral interface with queued transfer capability. It allows up to 16 transfers to be queued at once, minimizing the need for CPU intervention between transfers.

1.2.11 Fast ADC

The fast ADC consists of an eight-channel input select multiplexer and two independent sample and hold (S/H) circuits feeding separate 12-bit ADCs. The two separate converters store their results in accessible buffers for further processing.

The ADC can be configured to perform a single scan and halt, a scan when triggered, or a programmed scan sequence repeatedly until manually stopped.

The ADC can be configured for sequential or simultaneous conversion. When configured for sequential conversions, up to eight channels can be sampled and stored in any order specified by the channel list register. Both ADCs may be required during a scan, depending on the inputs to be sampled.

During a simultaneous conversion, both S/H circuits are used to capture two different channels at the same time. This configuration requires that a single channel may not be sampled by both S/H circuits simultaneously.

Optional interrupts can be generated at the end of the scan sequence if a channel is out of range (measures below the low threshold limit or above the high threshold limit set in the limit registers) or at several different zero crossing conditions.

1.2.12 DMA Timers (DTIM0–DTIM3)

There are four independent, DMA transfer capable 32-bit timers (DTIM0, DTIM1, DTIM2, and DTIM3) on the device. Each module incorporates a 32-bit timer with a separate register set for configuration and control. The timers can be configured to operate from the system clock or from an external clock source using one of the DTIN*n* signals. If the system clock is selected, it can be divided by 16 or 1. The input clock is further divided by a user-programmable 8-bit prescaler that clocks the actual timer counter register (TCR*n*). Each of these timers can be configured for input capture or reference (output) compare mode. Timer events may optionally cause interrupt requests or DMA transfers.

Table 13 shows the pin functions by primary and alternate purpose, and illustrates which packages contain each pin.

Table 4. Pin Functions by Primary and Alternate Purpose

Pin Group	Primary Function	Secondary Function	Tertiary Function	Quaternary Function	Drive Strength / Control[1]	Slew Rate / Control[1]	Pull-up / Pull-down[2]	Pin on 100 LQFP	Pin on 81 MAPBGA	Pin on 64 LQFP
ADC	AN7	—	—	GPIO	Low	FAST	—	51	H9	33
	AN6	—	—	GPIO	Low	FAST	—	52	G9	34
	AN5	—	—	GPIO	Low	FAST	—	53	G8	35
	AN4	—	—	GPIO	Low	FAST	—	54	F9	36
	AN3	—	—	GPIO	Low	FAST	—	46	G7	28
	AN2	—	—	GPIO	Low	FAST	—	45	G6	27
	AN1	—	—	GPIO	Low	FAST	—	44	H6	26
	AN0	—	—	GPIO	Low	FAST	—	43	J6	25
	SYNCA[3]	—	—	—	N/A	N/A	—	—	—	—
	SYNCB[3]	—	—	—	N/A	N/A	—	—	—	—
	VDDA	—	—	—	N/A	N/A	—	50	H8	32
	VSSA	—	—	—	N/A	N/A	—	47	H7, J9	29
	VRH	—	—	—	N/A	N/A	—	49	J8	31
	VRL	—	—	—	N/A	N/A	—	48	J7	30
Clock Generation	EXTAL	—	—	—	N/A	N/A	—	73	B9	47
	XTAL	—	—	—	N/A	N/A	—	72	C9	46
	VDDPLL	—	—	—	N/A	N/A	—	74	B8	48
	VSSPLL	—	—	—	N/A	N/A	—	71	C8	45
Debug Data	ALLPST	—	—	—	High	FAST	—	86	A6	55
	DDATA[3:0]	—	—	GPIO	High	FAST	—	84,83,78,77	—	—
	PST[3:0]	—	—	GPIO	High	FAST	—	70,69,66,65	—	—
I^2C	SCL	USB_DMI	UTXD2	GPIO	PDSR[0]	PSRR[0]	pull-up[4]	10	E1	8
	SDA	USB_DPI	URXD2	GPIO	PDSR[0]	PSRR[0]	pull-up[4]	11	E2	9

Table 4. Pin Functions by Primary and Alternate Purpose (continued)

Pin Group	Primary Function	Secondary Function	Tertiary Function	Quaternary Function	Drive Strength / Control[1]	Slew Rate / Control[1]	Pull-up / Pull-down[2]	Pin on 100 LQFP	Pin on 81 MAPBGA	Pin on 64 LQFP
Interrupts	$\overline{\text{IRQ7}}$	—	—	GPIO	Low	FAST	—	95	C4	58
	$\overline{\text{IRQ6}}$	—	—	GPIO	Low	FAST	—	94	B4	—
	$\overline{\text{IRQ5}}$	—	—	GPIO	Low	FAST	—	91	A4	—
	$\overline{\text{IRQ4}}$	—	—	GPIO	Low	FAST	—	90	C5	57
	$\overline{\text{IRQ3}}$	—	—	GPIO	Low	FAST	—	89	A5	—
	$\overline{\text{IRQ2}}$	—	—	GPIO	Low	FAST	—	88	B5	—
	$\overline{\text{IRQ1}}$	SYNCA	USB_ALT_CLK	GPIO	High	FAST	pull-up[4]	87	C6	56
JTAG/BDM	JTAG_EN	—	—	—	N/A	N/A	pull-down	26	J2	17
	TCLK/ PSTCLK	CLKOUT	—	—	High	FAST	pull-up[5]	64	C7	44
	TDI/DSI	—	—	—	N/A	N/A	pull-up[5]	79	B7	50
	TDO/DSO	—	—	—	High	FAST	—	80	A7	51
	TMS /$\overline{\text{BKPT}}$	—	—	—	N/A	N/A	pull-up[5]	76	A8	49
	$\overline{\text{TRST}}$ /DSCLK	—	—	—	N/A	N/A	pull-up[5]	85	B6	54
Mode Selection[6]	CLKMOD0	—	—	—	N/A	N/A	pull-down[6]	40	G5	24
	CLKMOD1	—	—	—	N/A	N/A	pull-down[6]	39	H5	—
	$\overline{\text{RCON}}$/ EZPCS	—	—	—	N/A	N/A	pull-up	21	G3	16

1.3 Reset Signals

Table 5 describes signals used to reset the chip or as a reset indication.

Table 5. Reset Signals

Signal Name	Abbreviation	Function	I/O
Reset In	$\overline{\text{RSTI}}$	Primary reset input to the device. Asserting $\overline{\text{RSTI}}$ for at least 8 CPU clock cycles immediately resets the CPU and peripherals.	I
Reset Out	$\overline{\text{RSTO}}$	Driven low for 1024 CPU clocks after the reset source has deasserted.	O

1.4 PLL and Clock Signals

Table 6 describes signals used to support the on-chip clock generation circuitry.

Table 6. PLL and Clock Signals

Signal Name	Abbreviation	Function	I/O
External Clock In	EXTAL	Crystal oscillator or external clock input except when the on-chip relaxation oscillator is used.	I
Crystal	XTAL	Crystal oscillator output except when CLKMOD0=0, then sampled as part of the clock mode selection mechanism.	O
Clock Out	CLKOUT	This output signal reflects the internal system clock.	O

1.5 Mode Selection

Table 7 describes signals used in mode selection; Table 8 describes the particular clocking modes.

Table 7. Mode Selection Signals

Signal Name	Abbreviation	Function	I/O
Clock Mode Selection	CLKMOD[1:0]	Selects the clock boot mode.	I
Reset Configuration	RCON	The Serial Flash Programming mode is entered by asserting the $\overline{\text{RCON}}$ pin (with the TEST pin negated) as the chip comes out of reset. During this mode, the EzPort has access to the flash memory which can be programmed from an external device.	
Test	TEST	Reserved for factory testing only and in normal modes of operation should be connected to VSS to prevent unintentional activation of test functions.	I

Table 8. Clocking Modes

CLKMOD[1:0]	XTAL	Configure the clock mode.
00	0	PLL disabled, clock driven by external oscillator
00	1	PLL disabled, clock driven by on-chip oscillator
01	N/A	PLL disabled, clock driven by crystal
10	0	PLL in normal mode, clock driven by external oscillator[1]
10	1	Reserved[2]
11	N/A	PLL in normal mode, clock driven by crystal[1]

[1] The PLL pre-divider (CCHR+1) reset value is 6 and the PLL input reference range is 2–10 MHz, so in order to boot with the PLL enabled, the external clock or crystal frequency needs to be greater than 12 MHz. MCF5222x devices cannot boot with PLL enabled from an external clock or crystal oscillator with frequency less than 12 MHz. This constraint does not apply to booting with PLL disabled.

[2] Cannot boot from the Internal 8 MHz Relaxation oscillator with the PLL enabled. Refer Note1. Thus this mode has been removed from the table.

1.6 External Interrupt Signals

Table 9 describes the external interrupt signals.

Table 9. External Interrupt Signals

Signal Name	Abbreviation	Function	I/O
External Interrupts	$\overline{\text{IRQ}}$[7:1]	External interrupt sources.	I

1.7 Queued Serial Peripheral Interface (QSPI)

Table 10 describes the QSPI signals.

Table 10. Queued Serial Peripheral Interface (QSPI) Signals

Signal Name	Abbreviation	Function	I/O
QSPI Synchronous Serial Output	QSPI_DOUT	Provides the serial data from the QSPI and can be programmed to be driven on the rising or falling edge of QSPI_CLK.	O
QSPI Synchronous Serial Data Input	QSPI_DIN	Provides the serial data to the QSPI and can be programmed to be sampled on the rising or falling edge of QSPI_CLK.	I
QSPI Serial Clock	QSPI_CLK	Provides the serial clock from the QSPI. The polarity and phase of QSPI_CLK are programmable.	O
Synchronous Peripheral Chip Selects	QSPI_CS[3:0]	QSPI peripheral chip select; can be programmed to be active high or low.	O

1.8 USB On-the-Go

This device is compliant with industry standard USB 2.0 specification.

1.9 I^2C I/O Signals

Table 11 describes the I^2C serial interface module signals.

Table 11. I^2C I/O Signals

Signal Name	Abbreviation	Function	I/O
Serial Clock	SCLn	Open-drain clock signal for the for the I^2C interface. When the bus is In master mode, this clock is driven by the I^2C module; when the bus is in slave mode, this clock becomes the clock input.	I/O
Serial Data	SDAn	Open-drain signal that serves as the data input/output for the I^2C interface.	I/O

1.10 UART Module Signals

Table 12 describes the UART module signals.

Table 12. UART Module Signals

Signal Name	Abbreviation	Function	I/O
Transmit Serial Data Output	UTXD*n*	Transmitter serial data outputs for the UART modules. The output is held high (mark condition) when the transmitter is disabled, idle, or in the local loopback mode. Data is shifted out, LSB first, on this pin at the falling edge of the serial clock source.	O
Receive Serial Data Input	URXD*n*	Receiver serial data inputs for the UART modules. Data is received on this pin LSB first. When the UART clock is stopped for power-down mode, any transition on this pin restarts the clock.	I
Clear-to-Send	$\overline{\text{UCTS}}$*n*	Indication to the UART modules that they can begin data transmission.	I
Request-to-Send	$\overline{\text{URTS}}$*n*	Automatic request-to-send outputs from the UART modules. This signal can also be configured to be asserted and negated as a function of the RxFIFO level.	O

1.11 DMA Timer Signals

Table 13 describes the signals of the four DMA timer modules.

Table 13. DMA Timer Signals

Signal Name	Abbreviation	Function	I/O
DMA Timer Input	DTIN	Event input to the DMA timer modules.	I
DMA Timer Output	DTOUT	Programmable output from the DMA timer modules.	O

1.12 ADC Signals

Table 14 describes the signals of the Analog-to-Digital Converter.

Table 14. ADC Signals

Signal Name	Abbreviation	Function	I/O
Analog Inputs	AN[7:0]	Inputs to the analog-to-digital converter.	I
Analog Reference	V_{RH}	Reference voltage high and low inputs.	I
	V_{RL}		I
Analog Supply	V_{DDA}	Isolate the ADC circuitry from power supply noise.	—
	V_{SSA}		—
ADC Sync Inputs	SYNCA / SYNCB	These signals can initiate an analog-to-digital conversion process.	I

Table 17. Debug Support Signals (continued)

Signal Name	Abbreviation	Function	I/O
Development Serial Input	DSI	Development Serial Input - Internally synchronized input that provides data input for the serial communication port to the debug module, after the DSCLK has been seen as high (logic 1).	I
Development Serial Output	DSO	Development Serial Output - Provides serial output communication for debug module responses. DSO is registered internally. The output is delayed from the validation of DSCLK high.	O
Debug Data	DDATA[3:0]	Display captured processor data and breakpoint status. The CLKOUT signal can be used by the development system to know when to sample DDATA[3:0].	O
Processor Status Clock	PSTCLK	Processor Status Clock - Delayed version of the processor clock. Its rising edge appears in the center of valid PST and DDATA output. PSTCLK indicates when the development system should sample PST and DDATA values. If real-time trace is not used, setting CSR[PCD] keeps PSTCLK, and PST and DDATA outputs from toggling without disabling triggers. Non-quiescent operation can be reenabled by clearing CSR[PCD], although the external development systems must resynchronize with the PST and DDATA outputs. PSTCLK starts clocking only when the first non-zero PST value (0xC, 0xD, or 0xF) occurs during system reset exception processing.	O
Processor Status Outputs	PST[3:0]	Indicate core status. Debug mode timing is synchronous with the processor clock; status is unrelated to the current bus transfer. The CLKOUT signal can be used by the development system to know when to sample PST[3:0].	O
All Processor Status Outputs	ALLPST	Logical AND of PST[3:0]. The CLKOUT signal can be used by the development system to know when to sample ALLPST.	O

1.16 EzPort Signal Descriptions

Table 18 contains a list of EzPort external signals.

Table 18. EzPort Signal Descriptions

Signal Name	Abbreviation	Function	I/O
EzPort Clock	EZPCK	Shift clock for EzPort transfers.	I
EzPort Chip Select	EZPCS	Chip select for signalling the start and end of serial transfers.	I
EzPort Serial Data In	EZPD	EZPD is sampled on the rising edge of EZPCK.	I
EzPort Serial Data Out	EZPQ	EZPQ transitions on the falling edge of EZPCK.	O

1.17 Power and Ground Pins

The pins described in Table 19 provide system power and ground to the chip. Multiple pins are provided for adequate current capability. All power supply pins must have adequate bypass capacitance for high-frequency noise suppression.

Table 19. Power and Ground Pins

Signal Name	Abbreviation	Function
PLL Analog Supply	VDDPLL, VSSPLL	Dedicated power supply signals to isolate the sensitive PLL analog circuitry from the normal levels of noise present on the digital power supply.
USB Power Supply	V_{DD}USB	This pin supplies power to the USB Module.
USB Ground Supply	V_{SS}USB	This pin is the negative (ground) supply pin for the USB Module.
Positive Supply	VDD	These pins supply positive power to the core logic.
Ground	VSS	This pin is the negative supply (ground) to the chip.

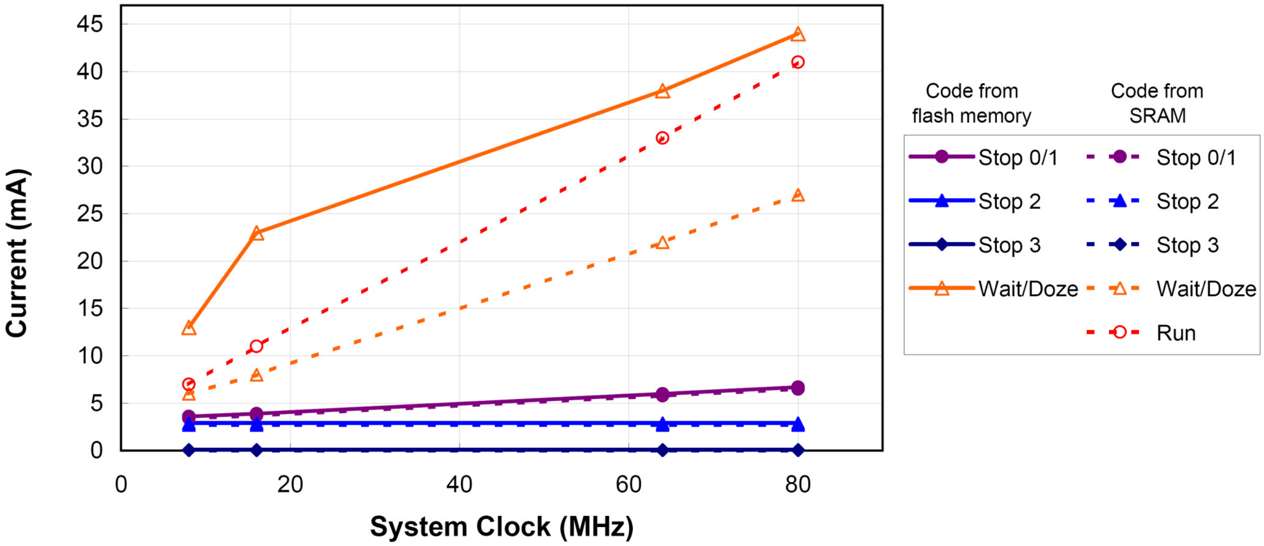

Figure 5. Plot of Current Consumption in Low-Power Modes

Table 23. Typical Active Current Consumption Specifications

Characteristic	Symbol	Typical[1] Active (SRAM)	Typical[1] Active (Flash)	Peak[2] Active (Flash)	Unit
8 MHz core & I/O	I_{DD}	8	11	18	mA
16 MHz core & I/O		11	19	33	
64 MHz core & I/O		35	44	82	
80 MHz core & I/O		43	52	98	
RAM standby supply current • Normal operation: $V_{DD} > V_{STBY}$ - 0.3 V • Transient condition: V_{STBY} - 0.3 V > $V_{DD} > V_{SS}$ + 0.5 V • Standby operation: $V_{DD} < V_{SS}$ + 0.5 V	I_{STBY}	 — — —		 0.4 TBD 16	µA
Analog supply current • Normal operation • Standby mode • Powered down	I_{DDA}	 2^(see note 3) — —		 13 TBD 0	mA
USB supply current	I_{DDUSB}	—		2	mA
PLL supply current	I_{DDPLL}	—		6^(see note 4)	mA

[1] Tested at room temperature with CPU polling a status register. All clocks were off except the UART and CFM (when running from flash memory).

[2] Peak current measured with all modules active, CPU polling a status register, and default drive strength with matching load.

[3] Tested using Auto Power Down (APD), which powers down the ADC between conversions; ADC running at 4 MHz in Once Parallel mode with a sample rate of 3 kHz.

[4] Tested with the PLL MFD set to 7 (max value). Setting the MFD to a lower value results in lower current consumption.

2.3 Thermal Characteristics

Table 24 lists thermal resistance values.

Table 24. Thermal Characteristics

	Characteristic		Symbol	Value	Unit
100 LQFP	Junction to ambient, natural convection	Single layer board (1s)	θ_{JA}	53[1,2]	°C/W
	Junction to ambient, natural convection	Four layer board (2s2p)	θ_{JA}	39[1,3]	°C/W
	Junction to ambient, (@200 ft/min)	Single layer board (1s)	θ_{JMA}	42[1,3]	°C/W
	Junction to ambient, (@200 ft/min)	Four layer board (2s2p)	θ_{JMA}	33[1,3]	°C/W
	Junction to board	—	θ_{JB}	25[4]	°C/W
	Junction to case	—	θ_{JC}	9[5]	°C/W
	Junction to top of package	Natural convection	Ψ_{jt}	2[6]	°C/W
	Maximum operating junction temperature	—	T_j	105	°C
81 MAPBGA	Junction to ambient, natural convection	Single layer board (1s)	θ_{JA}	61[1,2]	°C/W
	Junction to ambient, natural convection	Four layer board (2s2p)	θ_{JA}	35[2,3]	°C/W
	Junction to ambient, (@200 ft/min)	Single layer board (1s)	θ_{JMA}	50[2,3]	°C/W
	Junction to ambient, (@200 ft/min)	Four layer board (2s2p)	θ_{JMA}	31[2,3]	°C/W
	Junction to board	—	θ_{JB}	20[4]	°C/W
	Junction to case	—	θ_{JC}	12[5]	°C/W
	Junction to top of package	Natural convection	Ψ_{jt}	2[6]	°C/W
	Maximum operating junction temperature	—	T_j	105	°C
64 LQFP	Junction to ambient, natural convection	Single layer board (1s)	θ_{JA}	62[1,2]	°C/W
	Junction to ambient, natural convection	Four layer board (2s2p)	θ_{JA}	43[1,3]	°C/W
	Junction to ambient (@200 ft/min)	Single layer board (1s)	θ_{JMA}	50[1,3]	°C/W
	Junction to ambient (@200 ft/min)	Four layer board (2s2p)	θ_{JMA}	36[1,3]	°C/W
	Junction to board	—	θ_{JB}	26[4]	°C/W
	Junction to case	—	θ_{JC}	9[5]	°C/W
	Junction to top of package	Natural convection	Ψ_{jt}	2[6]	°C/W
	Maximum operating junction temperature	—	T_j	105	°C

[1] θ_{JA} and Ψ_{jt} parameters are simulated in conformance with EIA/JESD Standard 51-2 for natural convection. Freescale recommends the use of θ_{JA} and power dissipation specifications in the system design to prevent device junction temperatures from exceeding the rated specification. System designers should be aware that device junction temperatures can be significantly influenced by board layout and surrounding devices. Conformance to the device junction temperature specification can be verified by physical measurement in the customer's system using the Ψ_{jt} parameter, the device power dissipation, and the method described in EIA/JESD Standard 51-2.

[2] Per JEDEC JESD51-2 with the single-layer board (JESD51-3) horizontal.

[3] Per JEDEC JESD51-6 with the board JESD51-7) horizontal.

[4] Thermal resistance between the die and the printed circuit board in conformance with JEDEC JESD51-8. Board temperature is measured on the top surface of the board near the package.

[5] Thermal resistance between the die and the case top surface as measured by the cold plate method (MIL SPEC-883 Method 1012.1).

[6] Thermal characterization parameter indicating the temperature difference between package top and the junction temperature per JEDEC JESD51-2. When Greek letters are not available, the thermal characterization parameter is written in conformance with Psi-JT.

The average chip-junction temperature (T_J) in °C can be obtained from:

$$T_J = T_A + (P_D \times \Theta_{JMA}) \quad (1)$$

Where:

T_A = ambient temperature, °C
Θ_{JA} = package thermal resistance, junction-to-ambient, °C/W
P_D = $P_{INT} + P_{I/O}$
P_{INT} = chip internal power, $I_{DD} \times V_{DD}$, watts
$P_{I/O}$ = power dissipation on input and output pins — user determined, watts

For most applications $P_{I/O} < P_{INT}$ and can be ignored. An approximate relationship between P_D and T_J (if $P_{I/O}$ is neglected) is:

$$P_D = K \div (T_J + 273°C) \quad (2)$$

Solving equations 1 and 2 for K gives:

$$K = P_D \times (T_A + 273\ °C) + \Theta_{JMA} \times P_D^{\ 2} \quad (3)$$

where K is a constant pertaining to the particular part. K can be determined from equation (3) by measuring P_D (at equilibrium) for a known T_A. Using this value of K, the values of P_D and T_J can be obtained by solving equations (1) and (2) iteratively for any value of T_A.

2.4 Flash Memory Characteristics

The flash memory characteristics are shown in Table 25 and Table 26.

Table 25. SGFM Flash Program and Erase Characteristics

(V_{DD} = 3.0 to 3.6 V)

Parameter	Symbol	Min	Typ	Max	Unit
System clock (read only)	$f_{sys(R)}$	0	—	66.67 or 80[1]	MHz
System clock (program/erase)[2]	$f_{sys(P/E)}$	0.15	—	66.67 or 80[1]	MHz

[1] Depending on packaging; see the orderable part number summary.
[2] Refer to the flash memory section for more information

Table 26. SGFM Flash Module Life Characteristics

(V_{DD} = 3.0 to 3.6 V)

Parameter	Symbol	Value	Unit
Maximum number of guaranteed program/erase cycles[1] before failure	P/E	10,000[2]	Cycles
Data retention at average operating temperature of 85°C	Retention	10	Years

[1] A program/erase cycle is defined as switching the bits from 1 → 0 → 1.
[2] Reprogramming of a flash memory array block prior to erase is not required.

2.9 General Purpose I/O Timing

GPIO can be configured for certain pins of the QSPI, DDR Control, timer, UART, Interrupt and USB interfaces. When in GPIO mode, the timing specification for these pins is given in Table 31 and Figure 6.

The GPIO timing is met under the following load test conditions:

- 50 pF / 50 Ω for high drive
- 25 pF / 25 Ω for low drive

Table 31. GPIO Timing

NUM	Characteristic	Symbol	Min	Max	Unit
G1	CLKOUT High to GPIO Output Valid	t_{CHPOV}	—	10	ns
G2	CLKOUT High to GPIO Output Invalid	t_{CHPOI}	1.5	—	ns
G3	GPIO Input Valid to CLKOUT High	t_{PVCH}	9	—	ns
G4	CLKOUT High to GPIO Input Invalid	t_{CHPI}	1.5	—	ns

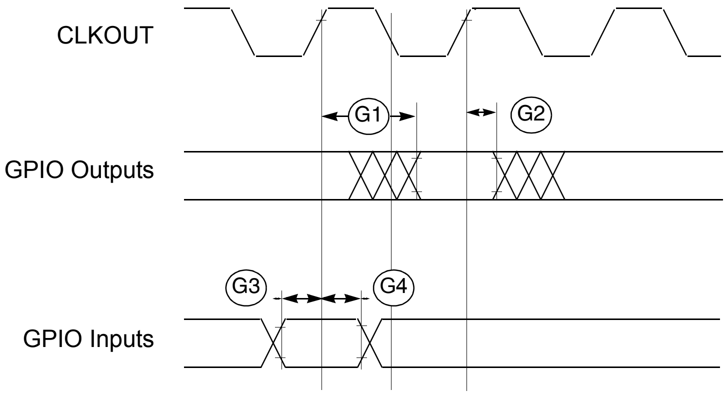

Figure 6. GPIO Timing

2.10 Reset Timing

Table 32. Reset and Configuration Override Timing

(V_{DD} = 3.0 to 3.6 V, V_{SS} = 0 V, $T_A = T_L$ to T_H)[1]

NUM	Characteristic	Symbol	Min	Max	Unit
R1	$\overline{\text{RSTI}}$ input valid to CLKOUT High	t_{RVCH}	9	—	ns
R2	CLKOUT High to $\overline{\text{RSTI}}$ Input invalid	t_{CHRI}	1.5	—	ns
R3	$\overline{\text{RSTI}}$ input valid time [2]	t_{RIVT}	5	—	t_{CYC}
R4	CLKOUT High to $\overline{\text{RSTO}}$ Valid	t_{CHROV}	—	10	ns

[1] All AC timing is shown with respect to 50% V_{DD} levels unless otherwise noted.

[2] During low power STOP, the synchronizers for the $\overline{\text{RSTI}}$ input are bypassed and $\overline{\text{RSTI}}$ is asserted asynchronously to the system. Thus, $\overline{\text{RSTI}}$ must be held a minimum of 100 ns.

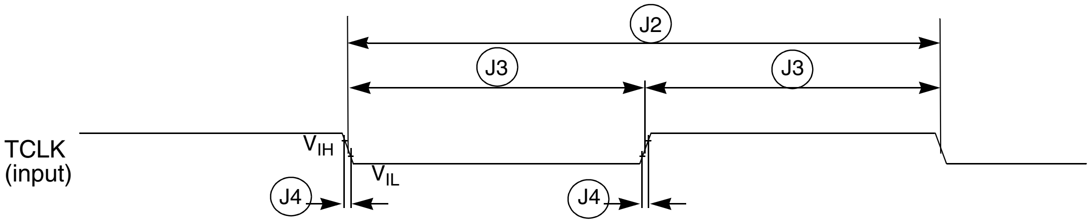

Figure 11. Test Clock Input Timing

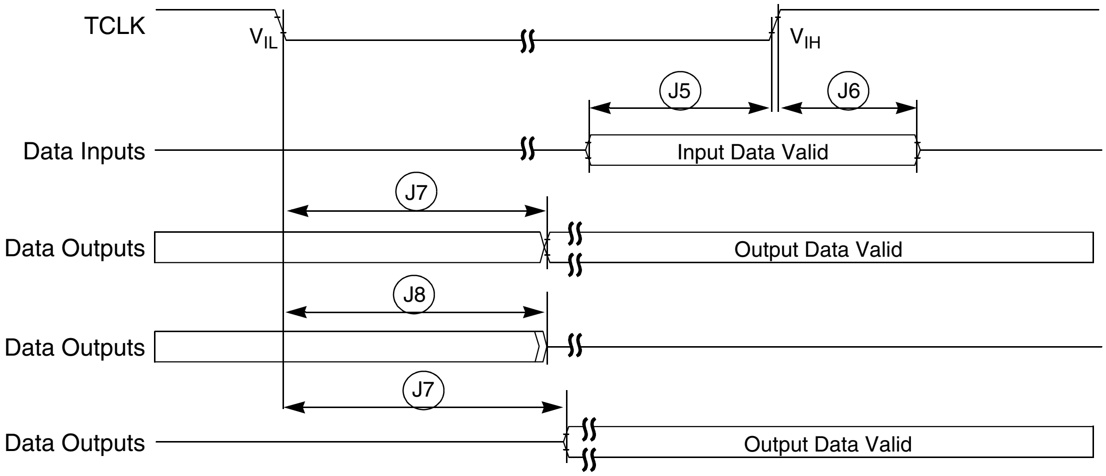

Figure 12. Boundary Scan (JTAG) Timing

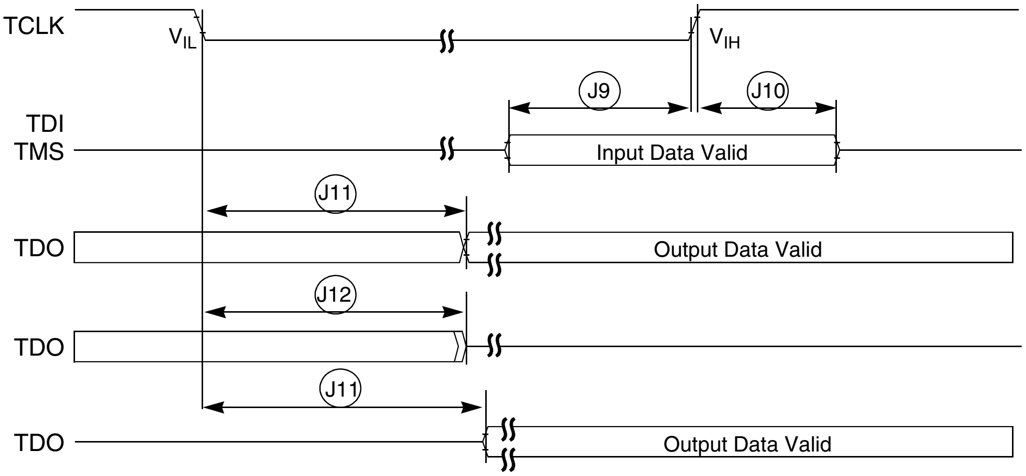

Figure 13. Test Access Port Timing

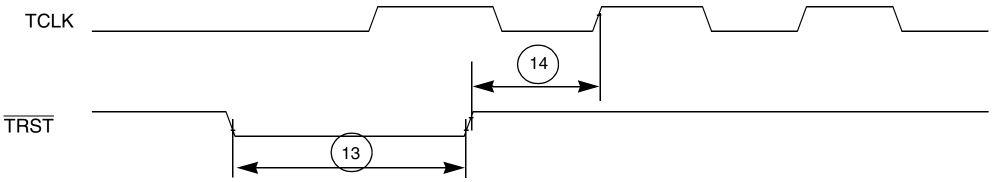

Figure 14. $\overline{\text{TRST}}$ Timing

MECHANICAL OUTLINES DICTIONARY

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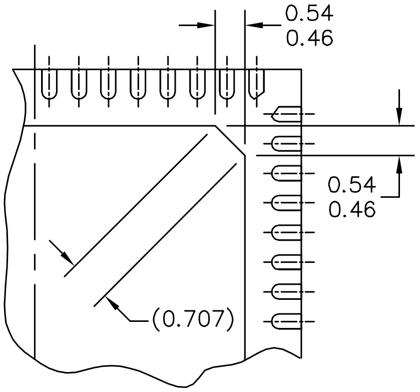

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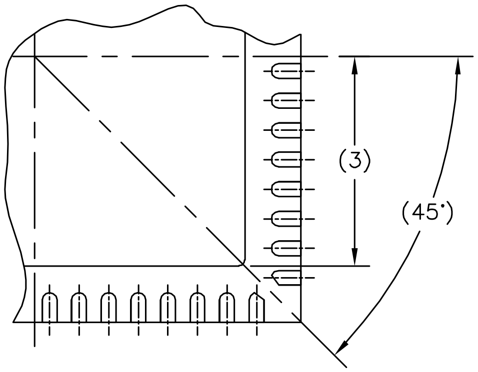
PREFERRED PIN1 BACKSIDE IDENTIFIER



DETAIL N
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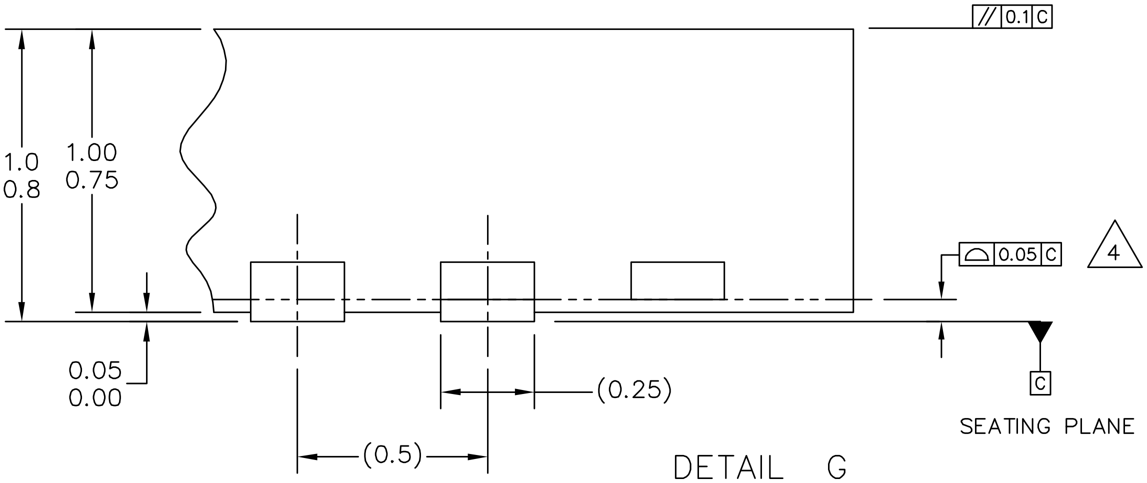

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FLAT NON–LEADED PACKAGE (QFN)
64 TERMINAL, 0.5 PITCH (9 X 9 X 1)

CASE NUMBER: 1740–01
STANDARD: JEDEC MO–220 VMMD–3
PACKAGE CODE: 6200
SHEET: 2 OF 4

REVISION HISTORY

DOCUMENT NO: 98ASA10690D
PAGE: 1740
REV: 0

LTR	ORIGINATOR	REVISIONS	DRAFTER	DATE
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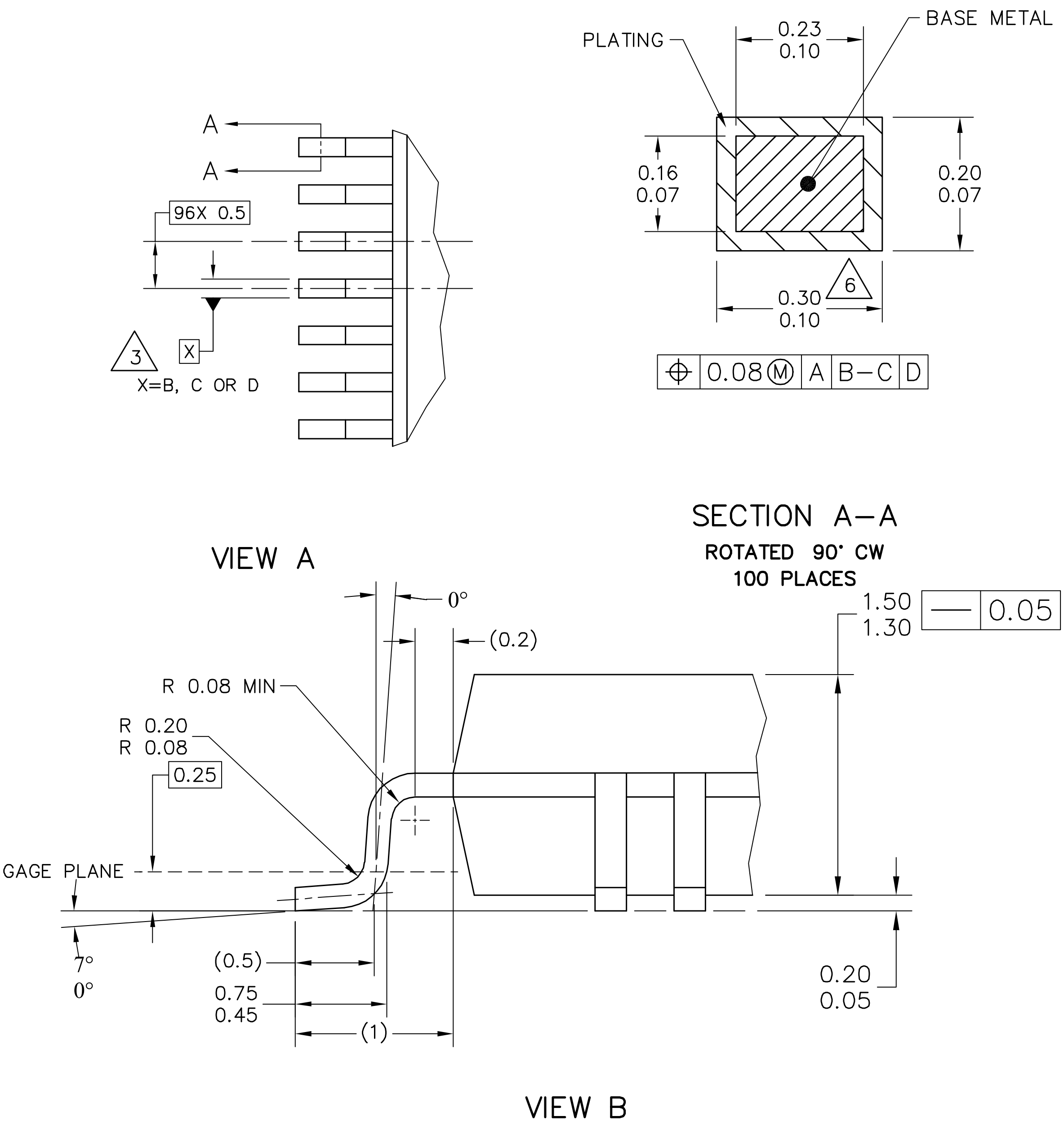
FLAT NON-LEADED PACKAGE (QFN)
64 TERMINAL, 0.5 PITCH (9 X 9 X 1)

CASE NUMBER: 1740-01
STANDARD: JEDEC MO-220 VMMD-3
PACKAGE CODE: 6200
SHEET: 4 OF 4



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	CASE NUMBER: 983–03	07 APR 2005
	STANDARD: NON–JEDEC	

4 Revision History

Table 40. Revision History

Revision	Description
2	• Formatting, layout, spelling, and grammar corrections. • Removed the “Preliminary” label. • Added missing current consumption data (Section 2.2). • Added revision history. • Corrected signal names in block diagram to match those in the signal description table. • Added an entry for standby voltage (V_{STBY}) to the “DC electrical specifications” table. • Deleted the PSTCLK cycle time row in the “Debug AC timing specifications” table. • Changed the frequency above the “Min” and “Max” column headings in the “Debug AC timing specifications” table (was 166 MHz, is 66/80 MHz). • Added the following signals to the “Pin functions by primary and alternate purpose” table (alternates to IRQ1-6, respectively): USB_ALT_CLK, USB_SESSVLD, USB_SESSEND, USB_PULLUP, USB_VBUSVLD, and USB_ID. • Changed the minimum value for SNR, THD, SFDR, and SINAD in the “ADC parameters” table (was TBD, is “—”). • Added values for I_{OH} and I_{OL} to the “DC electrical specifications” table. • Added load test condition information to the “General Purpose I/O Timing” section. • Synchronized the “Pin Functions by Primary and Alternate Purpose” table in this document and the reference manual. • Added a specification for V_{DDUSB} to the “Absolute maximum ratings” table. • Added specifications for V_{LVD} and V_{LVDHYS} to the “DC electrical specifications” table. • Deleted entries for the nonexistent 64 QFN package from the “Thermal Resistances” table.
3	• Updated Table 7 to reflect orderable part numbers.
4	• Updated Clock generation features • Updated Table: Clocking Modes and added appropriate footnote • In Table: CLock Source Electrical Specifications, updated the following values: • fcrystal, fext, fref_pll, EXTAL input high voltage (External reference)

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